Claims

1. A semiconductor substrate cleaning method comprising a step of removing an adhesive layer provided on a semiconductor substrate by use of a remover composition, wherein

the remover composition contains a solvent but no salt; and

the solvent comprises a C8 to C10 linear-chain, saturated, aliphatic hydrocarbon compound,

wherein the adhesive layer is a film formed from an adhesive composition comprising an adhesive component (S) containing a siloxane adhesive.

2. A semiconductor substrate cleaning method according to claim 1, wherein the C8 to C10 linear-chain, saturated, aliphatic hydrocarbon compound is at least one species selected from among n-octane, n-nonane, and n-decane.

3. A semiconductor substrate cleaning method according to claim 1 or 2, wherein the adhesive component (S) further comprises at least one species selected from among an acrylic resin adhesive, an epoxy resin adhesive, a polyamide adhesive, a polystyrene adhesive, a polyimide adhesive, and a phenolic resin adhesive.

4. A semiconductor substrate cleaning method according to any one of claims 1 to 3, wherein the siloxane adhesive contains a polyorganosiloxane component (A) which is curable through hydrosilylation.

5. A semiconductor substrate cleaning method according to any one of claims 1 to 4, wherein the adhesive composition contains a releasing agent component (B).

6. A semiconductor substrate cleaning method according to claim 5, wherein the adhesive composition contains the releasing agent component (B) in an amount of 25 mass% or more, with respect to the adhesive component (S).

7. A processed semiconductor substrate production method comprising:

a first step of producing a laminate having a semiconductor substrate, a support substrate, and an adhesive layer formed from an adhesive composition, wherein the adhesive layer is a film formed from an adhesive composition comprising an adhesive component (S) containing a siloxane adhesive;

a second step of processing the semiconductor substrate of the produced laminate;

a third step of separating the semiconductor substrate and the adhesive layer from the support substrate; and

a fourth step of removing the adhesive layer on the semiconductor substrate by use of a remover composition, wherein

the remover composition contains a solvent but no salt; and

the solvent comprises a C8 to C10 linear-chain, saturated, aliphatic hydrocarbon compound.

8. A processed semiconductor substrate production method according to claim 7, wherein the C8 to C10 linear-chain, saturated, aliphatic hydrocarbon compound is at least one species selected from among n-octane, n-nonane, and n-decane.

9. A processed semiconductor substrate production method according to claim 7 or 8, wherein the adhesive component (S) further comprises at least one species selected from among an acrylic resin adhesive, an epoxy resin adhesive, a polyamide adhesive, a polystyrene adhesive, a polyimide adhesive, and a phenolic resin adhesive.

10. A processed semiconductor substrate production method according to any one of claims 7 to 9, wherein the siloxane adhesive contains a polyorganosiloxane component (A) which is curable through hydrosilylation.

11. A processed semiconductor substrate production method according to claim 9 or 10, wherein the adhesive composition contains a releasing agent component (B).

12. A processed semiconductor substrate production method according to claim 11, wherein the adhesive composition contains the releasing agent component (B) in an amount of 25 mass% or more, with respect to the adhesive component (S).

13. A remover composition configured to remove an adhesive layer provided on a semiconductor substrate in cleaning the semiconductor substrate, wherein the adhesive layer is a film formed from an adhesive composition

comprising an adhesive component (S) containing a siloxane adhesive, wherein

the remover composition contains a solvent but no salt; and

the solvent comprises a C8 to C10 linear-chain, saturated, aliphatic hydrocarbon compound.

14. A remover composition according to claim 13, wherein the C8 to C10 linear-chain, saturated, aliphatic hydrocarbon compound is at least one species selected from among n-octane, n-nonane, and n-decane.

15. A remover composition according to claim 13 or 14, wherein the adhesive component (S) further comprises at least one species selected from among an acrylic resin adhesive, an epoxy resin adhesive, a polyamide adhesive, a polystyrene adhesive, a polyimide adhesive, and a phenolic resin adhesive.

16. A remover composition according to any one of claims 13 to 15, wherein the siloxane adhesive contains a polyorganosiloxane component (A) which is curable through hydrosilylation.

17. A remover composition according to claim 16, wherein the adhesive composition contains a releasing agent component (B).

18. A remover composition according to claim 17, wherein the adhesive composition contains the releasing agent component (B) in an amount of 25 mass% or more, with respect to the adhesive component (S).